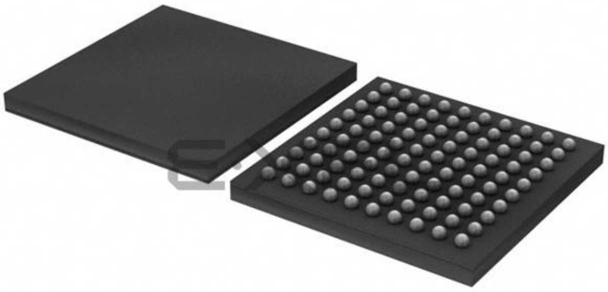
Microchip Technology - ATMEGA1280-16CUR Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8-Bit
Speed	16MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	86
Program Memory Size	128KB (64K x 16)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFBGA
Supplier Device Package	100-CBGA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atmega1280-16cur

1. Pin Configurations

Figure 1-1. TQFP-pinout ATmega640/1280/2560

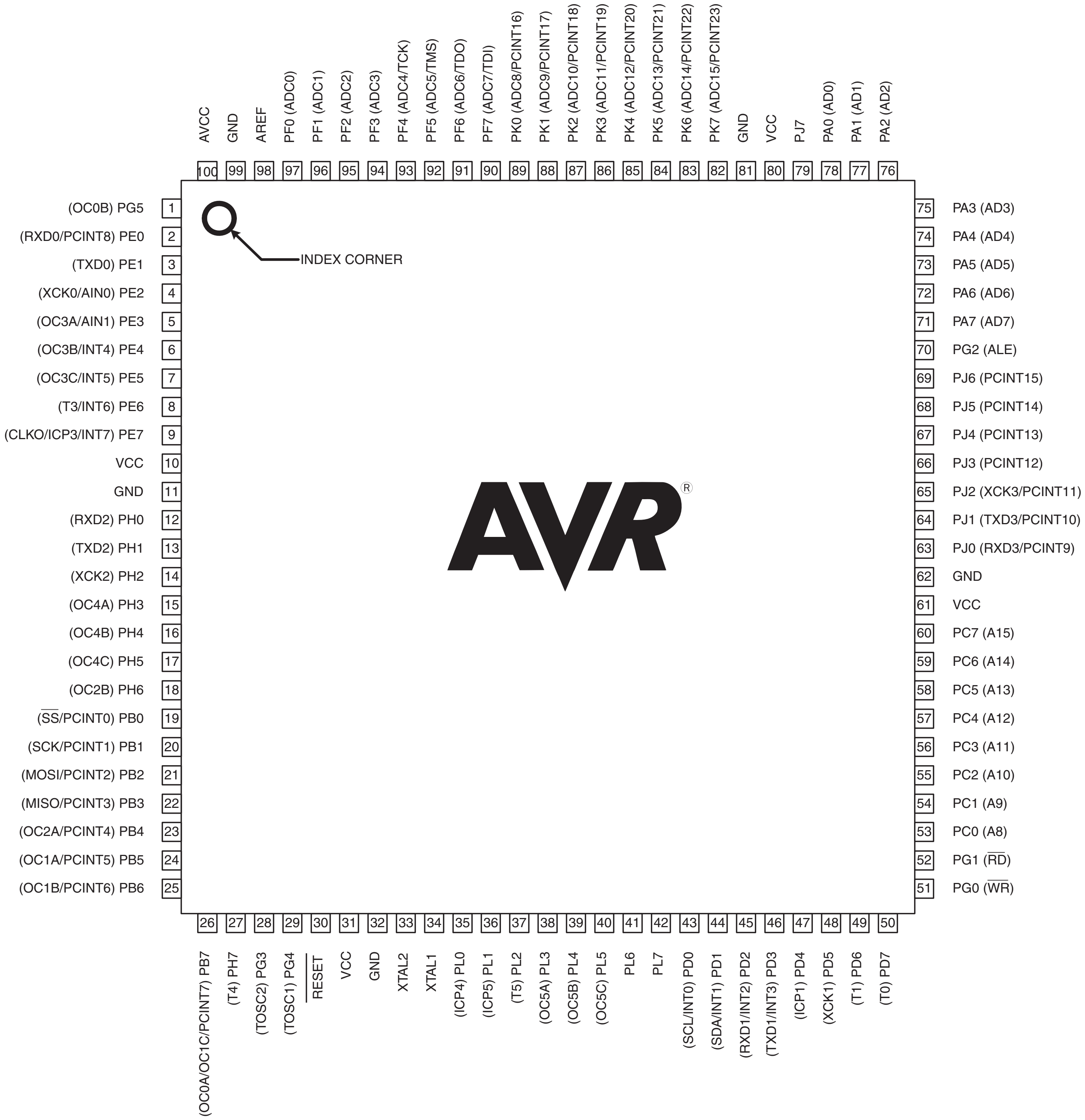


Figure 1-2. CBGA-pinout ATmega640/1280/2560

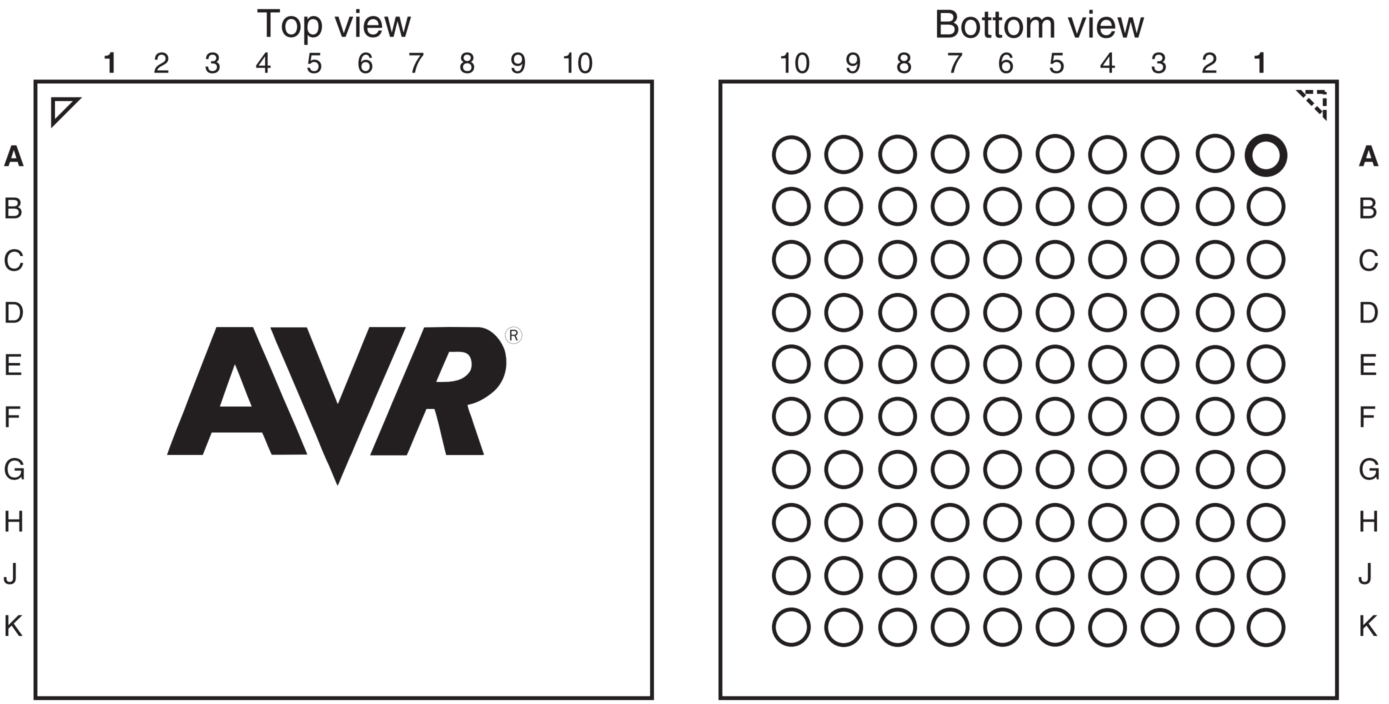
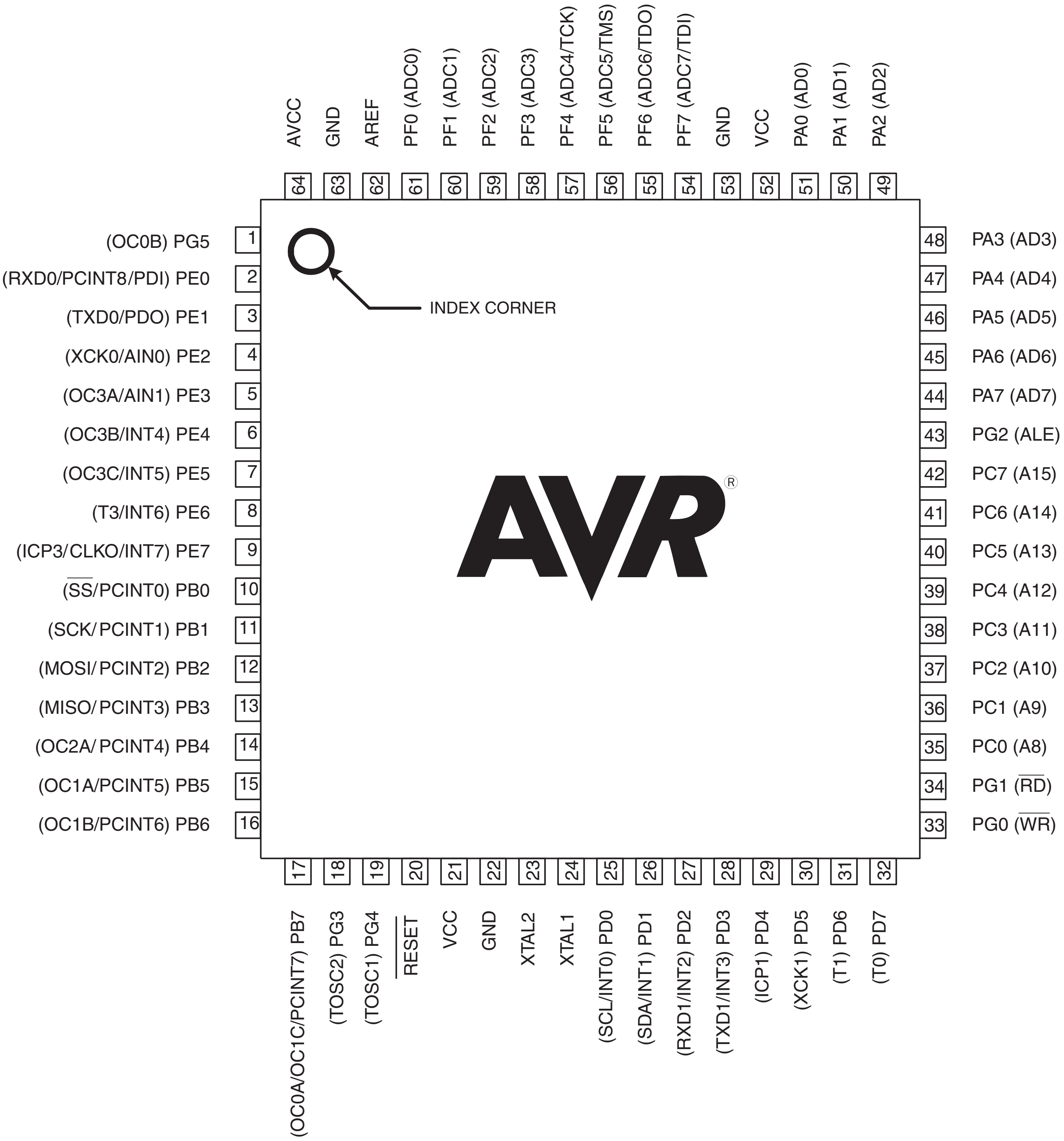


Table 1-1. CBGA-pinout ATmega640/1280/2560

	1	2	3	4	5	6	7	8	9	10
A	GND	AREF	PF0	PF2	PF5	PK0	PK3	PK6	GND	VCC
B	AVCC	PG5	PF1	PF3	PF6	PK1	PK4	PK7	PA0	PA2
C	PE2	PE0	PE1	PF4	PF7	PK2	PK5	PJ7	PA1	PA3
D	PE3	PE4	PE5	PE6	PH2	PA4	PA5	PA6	PA7	PG2
E	PE7	PH0	PH1	PH3	PH5	PJ6	PJ5	PJ4	PJ3	PJ2
F	VCC	PH4	PH6	PB0	PL4	PD1	PJ1	PJ0	PC7	GND
G	GND	PB1	PB2	PB5	PL2	PD0	PD5	PC5	PC6	VCC
H	PB3	PB4	RESET	PL1	PL3	PL7	PD4	PC4	PC3	PC2
J	PH7	PG3	PB6	PL0	XTAL2	PL6	PD3	PC1	PC0	PG1
K	PB7	PG4	VCC	GND	XTAL1	PL5	PD2	PD6	PD7	PG0

Note: The functions for each pin is the same as for the 100 pin packages shown in Figure 1-1 on page 2.

Figure 1-3. Pinout ATmega1281/2561



Note: The large center pad underneath the QFN/MLF package is made of metal and internally connected to GND. It should be soldered or glued to the board to ensure good mechanical stability. If the center pad is left unconnected, the package might loosen from the board.

The ATmega640/1280/1281/2560/2561 provides the following features: 64K/128K/256K bytes of In-System Programmable Flash with Read-While-Write capabilities, 4Kbytes EEPROM, 8Kbytes SRAM, 54/86 general purpose I/O lines, 32 general purpose working registers, Real Time Counter (RTC), six flexible Timer/Counters with compare modes and PWM, four USARTs, a byte oriented 2-wire Serial Interface, a 16-channel, 10-bit ADC with optional differential input stage with programmable gain, programmable Watchdog Timer with Internal Oscillator, an SPI serial port, IEEE® std. 1149.1 compliant JTAG test interface, also used for accessing the On-chip Debug system and programming and six software selectable power saving modes. The Idle mode stops the CPU while allowing the SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next interrupt or Hardware Reset. In Power-save mode, the asynchronous timer continues to run, allowing the user to maintain a timer base while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except Asynchronous Timer and ADC, to minimize switching noise during ADC conversions. In Standby mode, the Crystal/Resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low power consumption. In Extended Standby mode, both the main Oscillator and the Asynchronous Timer continue to run.

Atmel offers the QTouch® library for embedding capacitive touch buttons, sliders and wheels functionality into AVR microcontrollers. The patented charge-transfer signal acquisition offersrobust sensing and includes fully debounced reporting of touch keys and includes Adjacent Key Suppression® (AKS®) technology for unambiguous detection of key events. The easy-to-use QTouch Suite toolchain allows you to explore, develop and debug your own touch applications.

The device is manufactured using the Atmel high-density nonvolatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed in-system through an SPI serial interface, by a conventional non-volatile memory programmer, or by an On-chip Boot program running on the AVR core. The boot program can use any interface to download the application program in the application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the Atmel ATmega640/1280/1281/2560/2561 is a powerful microcontroller that provides a highly flexible and cost effective solution to many embedded control applications.

The ATmega640/1280/1281/2560/2561 AVR is supported with a full suite of program and system development tools including: C compilers, macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.

2.2 Comparison Between ATmega1281/2561 and ATmega640/1280/2560

Each device in the ATmega640/1280/1281/2560/2561 family differs only in memory size and number of pins. Table 2-1 summarizes the different configurations for the six devices.

Table 2-1. Configuration Summary

Device	Flash	EEPROM	RAM	General Purpose I/O pins	16 bits resolution PWM channels	Serial USARTs	ADC Channels
ATmega640	64KB	4KB	8KB	86	12	4	16
ATmega1280	128KB	4KB	8KB	86	12	4	16
ATmega1281	128KB	4KB	8KB	54	6	2	8
ATmega2560	256KB	4KB	8KB	86	12	4	16
ATmega2561	256KB	4KB	8KB	54	6	2	8

2.3 Pin Descriptions

2.3.1 VCC

Digital supply voltage.

2.3.2 GND

Ground.

2.3.3 Port A (PA7..PA0)

Port A is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port A output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port A pins that are externally pulled low will source current if the pull-up resistors are activated. The Port A pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port A also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 75.

2.3.4 Port B (PB7..PB0)

Port B is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port B output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port B pins that are externally pulled low will source current if the pull-up resistors are activated. The Port B pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B has better driving capabilities than the other ports.

Port B also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 76.

2.3.5 Port C (PC7..PC0)

Port C is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port C output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port C pins that are externally pulled low will source current if the pull-up resistors are activated. The Port C pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port C also serves the functions of special features of the ATmega640/1280/1281/2560/2561 as listed on page 79.

2.3.6 Port D (PD7..PD0)

Port D is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port D output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port D pins that are externally pulled low will source current if the pull-up resistors are activated. The Port D pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port D also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 80.

2.3.7 Port E (PE7..PE0)

Port E is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port E output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port E pins that are externally pulled low will source current if the pull-up resistors are activated. The Port E pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port E also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 82.

2.3.8 Port F (PF7..PF0)

Port F serves as analog inputs to the A/D Converter.

Port F also serves as an 8-bit bi-directional I/O port, if the A/D Converter is not used. Port pins can provide internal pull-up resistors (selected for each bit). The Port F output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port F pins that are externally pulled low will source current if the pull-up resistors are activated. The Port F pins are tri-stated when a reset condition becomes active, even if the clock is not running. If the JTAG interface is enabled, the pull-up resistors on pins PF7(TDI), PF5(TMS), and PF4(TCK) will be activated even if a reset occurs.

Port F also serves the functions of the JTAG interface.

2.3.9 Port G (PG5..PG0)

Port G is a 6-bit I/O port with internal pull-up resistors (selected for each bit). The Port G output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port G pins that are externally pulled low will source current if the pull-up resistors are activated. The Port G pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port G also serves the functions of various special features of the ATmega640/1280/1281/2560/2561 as listed on page 86.

2.3.10 Port H (PH7..PH0)

Port H is a 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port H output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port H pins that are externally pulled low will source current if the pull-up resistors are activated. The Port H pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port H also serves the functions of various special features of the ATmega640/1280/2560 as listed on page 88.

2.3.11 Port J (PJ7..PJ0)

Port J is a 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port J output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port J pins that are externally pulled low will source current if the pull-up resistors are activated. The Port J pins are tri-stated when a reset condition becomes active, even if the clock is not running. Port J also serves the functions of various special features of the ATmega640/1280/2560 as listed on page 90.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
(0x100)	PINH	PINH7	PINH6	PINH5	PINH4	PINH3	PINH2	PINH1	PINH0	page 99
(0xFF)	Reserved	-	-	-	-	-	-	-	-	
(0xFE)	Reserved	-	-	-	-	-	-	-	-	
(0xFD)	Reserved	-	-	-	-	-	-	-	-	
(0xFC)	Reserved	-	-	-	-	-	-	-	-	
(0xFB)	Reserved	-	-	-	-	-	-	-	-	
(0xFA)	Reserved	-	-	-	-	-	-	-	-	
(0xF9)	Reserved	-	-	-	-	-	-	-	-	
(0xF8)	Reserved	-	-	-	-	-	-	-	-	
(0xF7)	Reserved	-	-	-	-	-	-	-	-	
(0xF6)	Reserved	-	-	-	-	-	-	-	-	
(0xF5)	Reserved	-	-	-	-	-	-	-	-	
(0xF4)	Reserved	-	-	-	-	-	-	-	-	
(0xF3)	Reserved	-	-	-	-	-	-	-	-	
(0xF2)	Reserved	-	-	-	-	-	-	-	-	
(0xF1)	Reserved	-	-	-	-	-	-	-	-	
(0xF0)	Reserved	-	-	-	-	-	-	-	-	
(0xEF)	Reserved	-	-	-	-	-	-	-	-	
(0xEE)	Reserved	-	-	-	-	-	-	-	-	
(0xED)	Reserved	-	-	-	-	-	-	-	-	
(0xEC)	Reserved	-	-	-	-	-	-	-	-	
(0xEB)	Reserved	-	-	-	-		-	-	-	
(0xEA)	Reserved	-	-	-	-	-	-	-	-	
(0xE9)	Reserved	-	-	-	-	-	-	-	-	
(0xE8)	Reserved	-	-	-	-	-	-	-	-	
(0xE7)	Reserved	-	-	-	-		-	-	-	
(0xE6)	Reserved	-	-	-	-	-	-	-	-	
(0xE5)	Reserved	-	-	-	-	-	-	-	-	
(0xE4)	Reserved	-	-	-	-	-	-	-	-	
(0xE3)	Reserved	-	-	-	-		-	-	-	
(0xE2)	Reserved	-	-	-	-	-	-	-	-	
(0xE1)	Reserved	-	-	-	-		-	-	-	
(0xE0)	Reserved	-	-	-	-		-	-	-	
(0xDF)	Reserved	-	-	-	-	-	-	-	-	
(0xDE)	Reserved	-	-	-	-	-	-	-	-	
(0xDD)	Reserved	-	-	-	-		-	-	-	
(0xDC)	Reserved	-	-	-	-	-	-	-	-	
(0xDB)	Reserved	-	-	-	-	-	-	-	-	
(0xDA)	Reserved	-	-	-	-	-	-	-	-	
(0xD9)	Reserved	-	-	-	-		-	-	-	
(0xD8)	Reserved	-	-	-	-	-	-	-	-	
(0xD7)	Reserved	-	-	-	-	-	-	-	-	
(0xD6)	UDR2	USART2 I/O Data Register								page 218
(0xD5)	UBRR2H	-	-	-	-	USART2 Baud Rate Register High Byte				page 222
(0xD4)	UBRR2L	USART2 Baud Rate Register Low Byte								page 222
(0xD3)	Reserved	-	-	-	-	-	-	-	-	
(0xD2)	UCSR2C	UMSEL21	UMSEL20	UPM21	UPM20	USBS2	UCSZ21	UCSZ20	UCPOL2	page 235
(0xD1)	UCSR2B	RXCIE2	TXCIE2	UDRIE2	RXEN2	TXEN2	UCSZ22	RXB82	TXB82	page 234
(0xD0)	UCSR2A	RXC2	TXC2	UDRE2	FE2	DOR2	UPE2	U2X2	MPCM2	page 233
(0xCF)	Reserved	-	-	-	-	-	-	-	-	
(0xCE)	UDR1	USART1 I/O Data Register								page 218
(0xCD)	UBRR1H	-	-	-	-	USART1 Baud Rate Register High Byte				page 222
(0xCC)	UBRR1L	USART1 Baud Rate Register Low Byte								page 222
(0xCB)	Reserved	-	-	-	-	-	-	-	-	
(0xCA)	UCSR1C	UMSEL11	UMSEL10	UPM11	UPM10	USBS1	UCSZ11	UCSZ10	UCPOL1	page 235
(0xC9)	UCSR1B	RXCIE1	TXCIE1	UDRIE1	RXEN1	TXEN1	UCSZ12	RXB81	TXB81	page 234
(0xC8)	UCSR1A	RXC1	TXC1	UDRE1	FE1	DOR1	UPE1	U2X1	MPCM1	page 233
(0xC7)	Reserved	-	-	-	-	-	-	-	-	
(0xC6)	UDR0	USART0 I/O Data Register								page 218
(0xC5)	UBRR0H	-	-	-	-	USART0 Baud Rate Register High Byte				page 222
(0xC4)	UBRR0L	USART0 Baud Rate Register Low Byte								page 222
(0xC3)	Reserved	-	-	-	-	-	-	-	-	
(0xC2)	UCSR0C	UMSEL01	UMSEL00	UPM01	UPM00	USBS0	UCSZ01	UCSZ00	UCPOL0	page 235
(0xC1)	UCSR0B	RXCIE0	TXCIE0	UDRIE0	RXEN0	TXEN0	UCSZ02	RXB80	TXB80	page 234
(0xC0)	UCSR0A	RXC0	TXC0	UDRE0	FE0	DOR0	UPE0	U2X0	MPCM0	page 234
(0xBF)	Reserved	-	-	-	-	-	-	-	-	
(0xBE)	Reserved	-	-	-	-	-	-	-	-	
(0xBD)	TWAMR	TWAM6	TWAM5	TWAM4	TWAM3	TWAM2	TWAM1	TWAM0	-	page 264

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
(0x78)	ADCL	ADC Data Register Low byte								page 286
(0x77)	Reserved	-	-	-	-	-	-	-	-	
(0x76)	Reserved	-	-	-	-	-	-	-	-	
(0x75)	XMCRB	XMBK	-	-	-	-	XMM2	XMM1	XMM0	page 38
(0x74)	XMCRA	SRE	SRL2	SRL1	SRL0	SRW11	SRW10	SRW01	SRW00	page 36
(0x73)	TIMSK5	-	-	ICIE5	-	OCIE5C	OCIE5B	OCIE5A	TOIE5	page 162
(0x72)	TIMSK4	-	-	ICIE4	-	OCIE4C	OCIE4B	OCIE4A	TOIE4	page 161
(0x71)	TIMSK3	-	-	ICIE3	-	OCIE3C	OCIE3B	OCIE3A	TOIE3	page 161
(0x70)	TIMSK2	-	-	-	-	-	OCIE2B	OCIE2A	TOIE2	page 188
(0x6F)	TIMSK1	-	-	ICIE1	-	OCIE1C	OCIE1B	OCIE1A	TOIE1	page 161
(0x6E)	TIMSK0	-	-	-	-	-	OCIE0B	OCIE0A	TOIE0	page 131
(0x6D)	PCMSK2	PCINT23	PCINT22	PCINT21	PCINT20	PCINT19	PCINT18	PCINT17	PCINT16	page 113
(0x6C)	PCMSK1	PCINT15	PCINT14	PCINT13	PCINT12	PCINT11	PCINT10	PCINT9	PCINT8	page 113
(0x6B)	PCMSK0	PCINT7	PCINT6	PCINT5	PCINT4	PCINT3	PCINT2	PCINT1	PCINT0	page 114
(0x6A)	EICRB	ISC71	ISC70	ISC61	ISC60	ISC51	ISC50	ISC41	ISC40	page 110
(0x69)	EICRA	ISC31	ISC30	ISC21	ISC20	ISC11	ISC10	ISC01	ISC00	page 110
(0x68)	PCICR	-	-	-	-	-	PCIE2	PCIE1	PCIE0	page 112
(0x67)	Reserved	-	-	-	-	-	-	-	-	
(0x66)	OSCCAL	Oscillator Calibration Register								page 48
(0x65)	PRR1	-	-	PRTIM5	PRTIM4	PRTIM3	PRUSART3	PRUSART2	PRUSART1	page 56
(0x64)	PRR0	PRTWI	PRTIM2	PRTIM0	-	PRTIM1	PRSPI	PRUSART0	PRADC	page 55
(0x63)	Reserved	-	-	-	-	-	-	-	-	
(0x62)	Reserved	-	-	-	-	-	-	-	-	
(0x61)	CLKPR	CLKPCE	-	-	-	CLKPS3	CLKPS2	CLKPS1	CLKPS0	page 48
(0x60)	WDTCSR	WDIF	WDIE	WDP3	WDCE	WDE	WDP2	WDP1	WDP0	page 65
0x3F (0x5F)	SREG	I	T	H	S	V	N	Z	C	page 13
0x3E (0x5E)	SPH	SP15	SP14	SP13	SP12	SP11	SP10	SP9	SP8	page 15
0x3D (0x5D)	SPL	SP7	SP6	SP5	SP4	SP3	SP2	SP1	SP0	page 15
0x3C (0x5C)	EIND	-	-	-	-	-	-	-	EIND0	page 16
0x3B (0x5B)	RAMPZ	-	-	-	-	-	-	RAMPZ1	RAMPZ0	page 16
0x3A (0x5A)	Reserved	-	-	-	-	-	-	-	-	
0x39 (0x59)	Reserved	-	-	-	-	-	-	-	-	
0x38 (0x58)	Reserved	-	-	-	-	-	-	-	-	
0x37 (0x57)	SPMCSR	SPMIE	RWWSB	SIGRD	RWWSRE	BLBSET	PGWRT	PGERS	SPMEN	page 323
0x36 (0x56)	Reserved	-	-	-	-	-	-	-	-	
0x35 (0x55)	MCUCR	JTD	-	-	PUD	-	-	IVSEL	IVCE	page 64, 108, 96, 301
0x34 (0x54)	MCUSR	-	-	-	JTRF	WDRF	BORF	EXTRF	PORF	page 301
0x33 (0x53)	SMCR	-	-	-	-	SM2	SM1	SM0	SE	page 50
0x32 (0x52)	Reserved	-	-	-	-	-	-	-	-	
0x31 (0x51)	OCDR	OCDR7	OCDR6	OCDR5	OCDR4	OCDR3	OCDR2	OCDR1	OCDR0	page 294
0x30 (0x50)	ACSR	ACD	ACBG	ACO	ACI	ACIE	ACIC	ACIS1	ACIS0	page 266
0x2F (0x4F)	Reserved	-	-	-	-	-	-	-	-	
0x2E (0x4E)	SPDR	SPI Data Register								page 199
0x2D (0x4D)	SPSR	SPIF	WCOL	-	-	-	-	-	SPI2X	page 198
0x2C (0x4C)	SPCR	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	page 197
0x2B (0x4B)	GPIOR2	General Purpose I/O Register 2								page 36
0x2A (0x4A)	GPIOR1	General Purpose I/O Register 1								page 36
0x29 (0x49)	Reserved	-	-	-	-	-	-	-	-	
0x28 (0x48)	OCR0B	Timer/Counter0 Output Compare Register B								page 130
0x27 (0x47)	OCR0A	Timer/Counter0 Output Compare Register A								page 130
0x26 (0x46)	TCNT0	Timer/Counter0 (8 Bit)								page 130
0x25 (0x45)	TCCR0B	FOC0A	FOC0B	-	-	WGM02	CS02	CS01	CS00	page 129
0x24 (0x44)	TCCR0A	COM0A1	COM0A0	COM0B1	COM0B0	-	-	WGM01	WGM00	page 126
0x23 (0x43)	GTCCR	TSM	-	-	-	-	-	PSRASY	PSRSYNC	page 166, 189
0x22 (0x42)	EEARH	-	-	-	-	EEPROM Address Register High Byte				page 34
0x21 (0x41)	EEARL	EEPROM Address Register Low Byte								page 34
0x20 (0x40)	EEDR	EEPROM Data Register								page 34
0x1F (0x3F)	EECR	-	-	EEPM1	EEPM0	EERIE	EEMPE	EEPE	EERE	page 34
0x1E (0x3E)	GPIOR0	General Purpose I/O Register 0								page 36
0x1D (0x3D)	EIMSK	INT7	INT6	INT5	INT4	INT3	INT2	INT1	INT0	page 111
0x1C (0x3C)	EIFR	INTF7	INTF6	INTF5	INTF4	INTF3	INTF2	INTF1	INTF0	page 112
0x1B (0x3B)	PCIFR	-	-	-	-	-	PCIF2	PCIF1	PCIF0	page 113
0x1A (0x3A)	TIFR5	-	-	ICF5	-	OCF5C	OCF5B	OCF5A	TOV5	page 162
0x19 (0x39)	TIFR4	-	-	ICF4	-	OCF4C	OCF4B	OCF4A	TOV4	page 162
0x18 (0x38)	TIFR3	-	-	ICF3	-	OCF3C	OCF3B	OCF3A	TOV3	page 162
0x17 (0x37)	TIFR2	-	-	-	-	-	OCF2B	OCF2A	TOV2	page 188
0x16 (0x36)	TIFR1	-	-	ICF1	-	OCF1C	OCF1B	OCF1A	TOV1	page 162
0x15 (0x35)	TIFR0	-	-	-	-	-	OCF0B	OCF0A	TOV0	page 131

8. Instruction Set Summary

Mnemonics	Operands	Description	Operation	Flags	#Clocks
ARITHMETIC AND LOGIC INSTRUCTIONS					
ADD	Rd, Rr	Add two Registers	Rd ← Rd + Rr	Z, C, N, V, H	1
ADC	Rd, Rr	Add with Carry two Registers	Rd ← Rd + Rr + C	Z, C, N, V, H	1
ADIW	Rdl,K	Add Immediate to Word	Rdh:Rdl ← Rdh:Rdl + K	Z, C, N, V, S	2
SUB	Rd, Rr	Subtract two Registers	Rd ← Rd - Rr	Z, C, N, V, H	1
SUBI	Rd, K	Subtract Constant from Register	Rd ← Rd - K	Z, C, N, V, H	1
SBC	Rd, Rr	Subtract with Carry two Registers	Rd ← Rd - Rr - C	Z, C, N, V, H	1
SBCI	Rd, K	Subtract with Carry Constant from Reg.	Rd ← Rd - K - C	Z, C, N, V, H	1
SBIW	Rdl,K	Subtract Immediate from Word	Rdh:Rdl ← Rdh:Rdl - K	Z, C, N, V, S	2
AND	Rd, Rr	Logical AND Registers	Rd ← Rd • Rr	Z, N, V	1
ANDI	Rd, K	Logical AND Register and Constant	Rd ← Rd • K	Z, N, V	1
OR	Rd, Rr	Logical OR Registers	Rd ← Rd v Rr	Z, N, V	1
ORI	Rd, K	Logical OR Register and Constant	Rd ← Rd v K	Z, N, V	1
EOR	Rd, Rr	Exclusive OR Registers	Rd ← Rd ⊕ Rr	Z, N, V	1
COM	Rd	One's Complement	Rd ← 0xFF – Rd	Z, C, N, V	1
NEG	Rd	Two's Complement	Rd ← 0x00 – Rd	Z, C, N, V, H	1
SBR	Rd,K	Set Bit(s) in Register	Rd ← Rd v K	Z, N, V	1
CBR	Rd,K	Clear Bit(s) in Register	Rd ← Rd • (0xFF - K)	Z, N, V	1
INC	Rd	Increment	Rd ← Rd + 1	Z, N, V	1
DEC	Rd	Decrement	Rd ← Rd – 1	Z, N, V	1
TST	Rd	Test for Zero or Minus	Rd ← Rd • Rd	Z, N, V	1
CLR	Rd	Clear Register	Rd ← Rd ⊕ Rd	Z, N, V	1
SER	Rd	Set Register	Rd ← 0xFF	None	1
MUL	Rd, Rr	Multiply Unsigned	R1:R0 ← Rd x Rr	Z, C	2
MULS	Rd, Rr	Multiply Signed	R1:R0 ← Rd x Rr	Z, C	2
MULSU	Rd, Rr	Multiply Signed with Unsigned	R1:R0 ← Rd x Rr	Z, C	2
FMUL	Rd, Rr	Fractional Multiply Unsigned	R1:R0 ← (Rd x Rr) << 1	Z, C	2
FMULS	Rd, Rr	Fractional Multiply Signed	R1:R0 ← (Rd x Rr) << 1	Z, C	2
FMULSU	Rd, Rr	Fractional Multiply Signed with Unsigned	R1:R0 ← (Rd x Rr) << 1	Z, C	2
BRANCH INSTRUCTIONS					
RJMP	k	Relative Jump	PC ← PC + k + 1	None	2
IJMP		Indirect Jump to (Z)	PC ← Z	None	2
EIJMP		Extended Indirect Jump to (Z)	PC ←(EIND:Z)	None	2
JMP	k	Direct Jump	PC ← k	None	3
RCALL	k	Relative Subroutine Call	PC ← PC + k + 1	None	4
ICALL		Indirect Call to (Z)	PC ← Z	None	4
EICALL		Extended Indirect Call to (Z)	PC ←(EIND:Z)	None	4
CALL	k	Direct Subroutine Call	PC ← k	None	5
RET		Subroutine Return	PC ← STACK	None	5
RETI		Interrupt Return	PC ← STACK	I	5
CPSE	Rd,Rr	Compare, Skip if Equal	if (Rd = Rr) PC ← PC + 2 or 3	None	1/2/3
CP	Rd,Rr	Compare	Rd – Rr	Z, N, V, C, H	1
CPC	Rd,Rr	Compare with Carry	Rd – Rr – C	Z, N, V, C, H	1
CPI	Rd,K	Compare Register with Immediate	Rd – K	Z, N, V, C, H	1
SBRC	Rr, b	Skip if Bit in Register Cleared	if (Rr(b)=0) PC ← PC + 2 or 3	None	1/2/3
SBRS	Rr, b	Skip if Bit in Register is Set	if (Rr(b)=1) PC ← PC + 2 or 3	None	1/2/3
SBIC	P, b	Skip if Bit in I/O Register Cleared	if (P(b)=0) PC ← PC + 2 or 3	None	1/2/3
SBIS	P, b	Skip if Bit in I/O Register is Set	if (P(b)=1) PC ← PC + 2 or 3	None	1/2/3
BRBS	s, k	Branch if Status Flag Set	if (SREG(s) = 1) then PC←PC+k + 1	None	1/2
BRBC	s, k	Branch if Status Flag Cleared	if (SREG(s) = 0) then PC←PC+k + 1	None	1/2
BREQ	k	Branch if Equal	if (Z = 1) then PC ← PC + k + 1	None	1/2
BRNE	k	Branch if Not Equal	if (Z = 0) then PC ← PC + k + 1	None	1/2
BRCS	k	Branch if Carry Set	if (C = 1) then PC ← PC + k + 1	None	1/2
BRCC	k	Branch if Carry Cleared	if (C = 0) then PC ← PC + k + 1	None	1/2
BRSH	k	Branch if Same or Higher	if (C = 0) then PC ← PC + k + 1	None	1/2
BRLO	k	Branch if Lower	if (C = 1) then PC ← PC + k + 1	None	1/2
BRMI	k	Branch if Minus	if (N = 1) then PC ← PC + k + 1	None	1/2
BRPL	k	Branch if Plus	if (N = 0) then PC ← PC + k + 1	None	1/2
BRGE	k	Branch if Greater or Equal, Signed	if (N ⊕ V= 0) then PC ← PC + k + 1	None	1/2
BRLT	k	Branch if Less Than Zero, Signed	if (N ⊕ V= 1) then PC ← PC + k + 1	None	1/2
BRHS	k	Branch if Half Carry Flag Set	if (H = 1) then PC ← PC + k + 1	None	1/2
BRHC	k	Branch if Half Carry Flag Cleared	if (H = 0) then PC ← PC + k + 1	None	1/2
BRTS	k	Branch if T Flag Set	if (T = 1) then PC ← PC + k + 1	None	1/2
BRTC	k	Branch if T Flag Cleared	if (T = 0) then PC ← PC + k + 1	None	1/2
BRVS	k	Branch if Overflow Flag is Set	if (V = 1) then PC ← PC + k + 1	None	1/2

9.3 ATmega1281

Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8 - 5.5V	ATmega1281V-8AU ATmega1281V-8AUR[4] ATmega1281V-8MU ATmega1281V-8MUR[4]	64A 64A 64M2 64M2	Industrial (-40°C to 85°C)
16	2.7 - 5.5V	ATmega1281-16AU ATmega1281-16AUR[4] ATmega1281-16MU ATmega1281-16MUR[4]	64A 64A 64M2 64M2	

Notes:
1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See "Speed Grades" on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
64A	64-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
64M2	64-pad, 9mm × 9mm × 1.0mm Body, Quad Flat No-lead/Micro Lead Frame Package (QFN/MLF)

9.5 ATmega2561

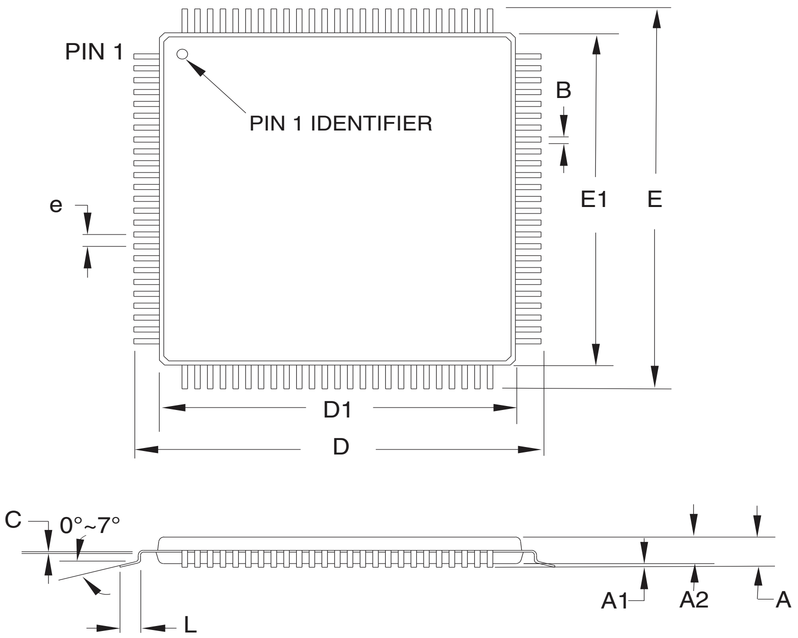
Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8V - 5.5V	ATmega2561V-8AU ATmega2561V-8AUR[4] ATmega2561V-8MU ATmega2561V-8MUR[4]	64A 64A 64M2 64M2	Industrial (-40°C to 85°C)
16	4.5V - 5.5V	ATmega2561-16AU ATmega2561-16AUR[4] ATmega2561-16MU ATmega2561-16MUR[4]	64A 64A 64M2 64M2	

Notes:
1. This device can also be supplied in wafer form.Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See "Speed Grades" on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
64A	64-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
64M2	64-pad, 9mm × 9mm × 1.0mm Body, Quad Flat No-lead/Micro Lead Frame Package (QFN/MLF)

10. Packaging Information

10.1 100A



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	15.75	16.00	16.25	
D1	13.90	14.00	14.10	Note 2
E	15.75	16.00	16.25	
E1	13.90	14.00	14.10	Note 2
B	0.17	–	0.27	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.50 TYP			

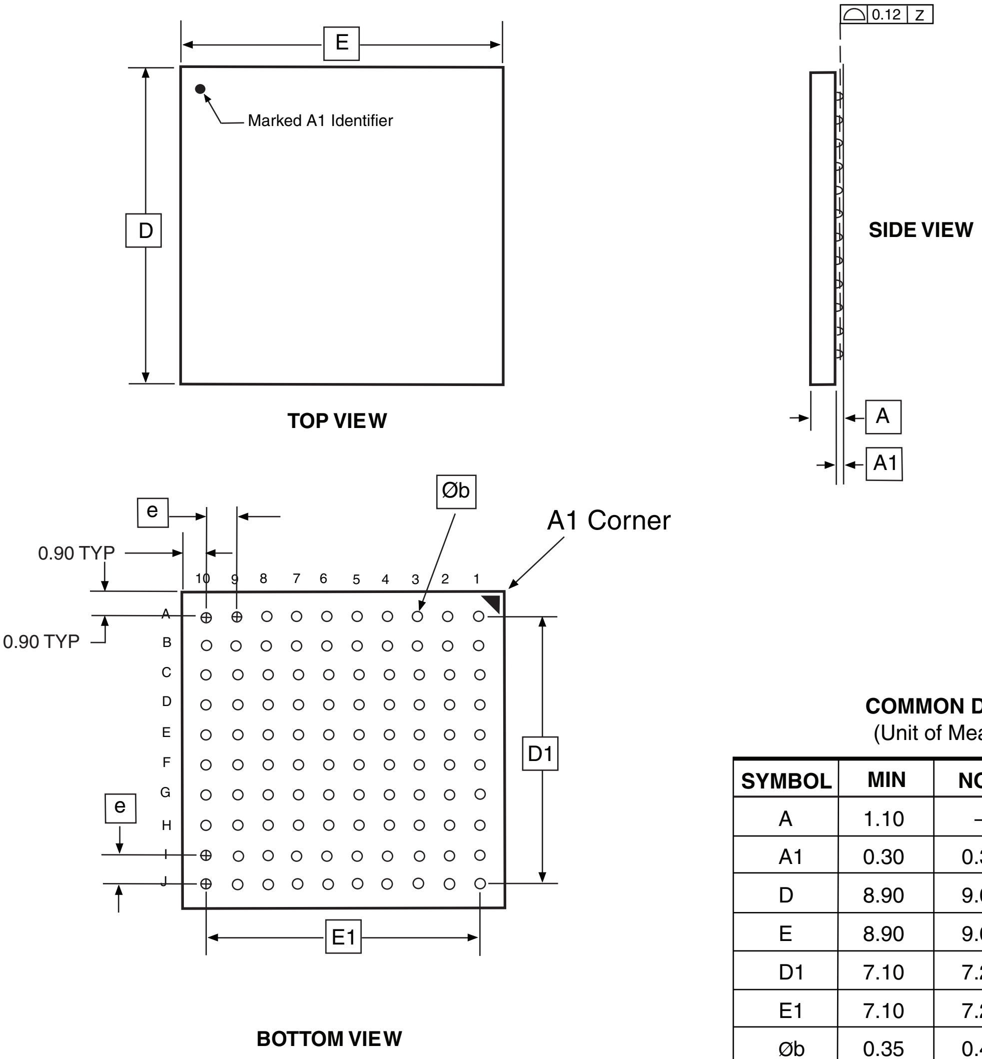
Notes:

1. This package conforms to JEDEC reference MS-026, Variation AED.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.08 mm maximum.

2010-10-20

Package Drawing Contact: **packagedrawings@atmel.com**	TITLE **100A**, 100-lead, 14 x 14 mm Body Size, 1.0 mm Body Thickness, 0.5 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	DRAWING NO. 100A	REV. D

10.2 100C1



COMMON DIMENSIONS
(Unit of Measure = mm)

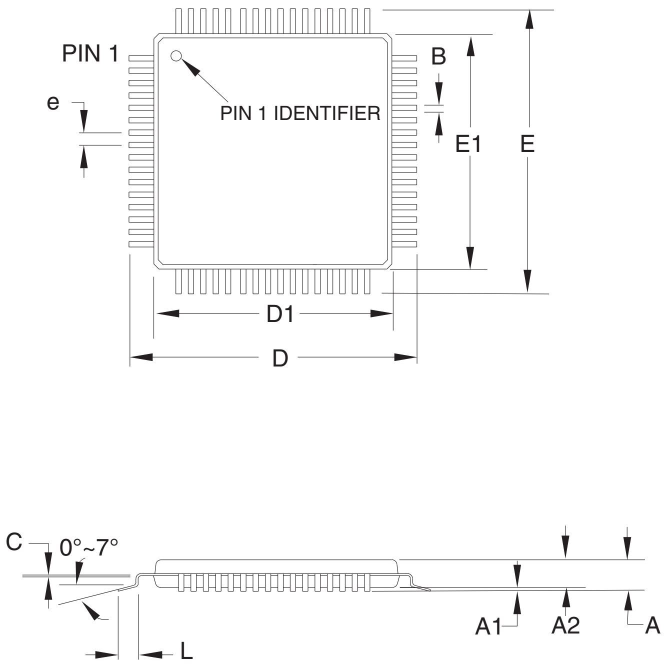
SYMBOL	MIN	NOM	MAX	NOTE
A	1.10	–	1.20	
A1	0.30	0.35	0.40	
D	8.90	9.00	9.10	
E	8.90	9.00	9.10	
D1	7.10	7.20	7.30	
E1	7.10	7.20	7.30	
Øb	0.35	0.40	0.45	
e	0.80 TYP			

5/25/06

2325 Orchard Parkway
San Jose, CA 95131

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**100C1**, 100-ball, 9 x 9 x 1.2 mm Body, Ball Pitch 0.80 mm Chip Array BGA Package (CBGA)	100C1	A

10.3 64A



COMMON DIMENSIONS
(Unit of measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	15.75	16.00	16.25	
D1	13.90	14.00	14.10	Note 2
E	15.75	16.00	16.25	
E1	13.90	14.00	14.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

Notes:
1. This package conforms to JEDEC reference MS-026, Variation AEB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

2010-10-20

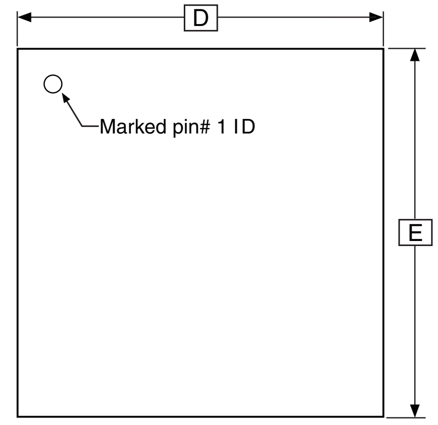
2325 Orchard Parkway
San Jose, CA 95131

TITLE
64A, 64-lead, 14 x 14mm Body Size, 1.0mm Body Thickness,
0.8mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)

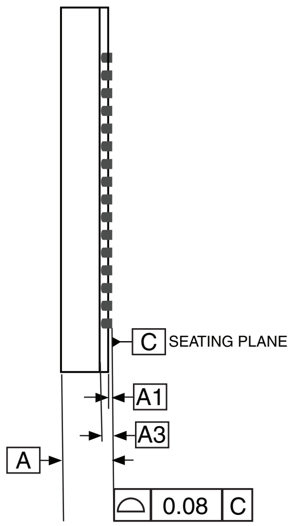
DRAWING NO. 64A

REV. C

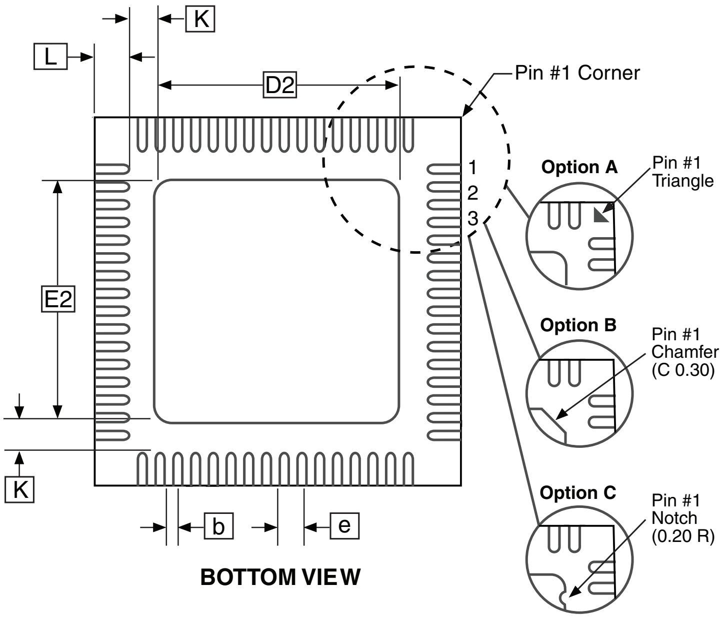
10.4 64M2



TOP VIEW



SIDE VIEW



BOTTOM VIEW

COMMON DIMENSIONS
(Unit of measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	0.90	1.00	
A1	–	0.02	0.05	
A3		0.20 REF		
b	0.18	0.25	0.30	
D	8.90	9.00	9.10	
D2	7.50	7.65	7.80	
E	8.90	9.00	9.10	
E2	7.50	7.65	7.80	
e		0.50 BSC		
L	0.35	0.40	0.45	
K	0.20	0.27	0.40	

Notes: 1. JEDEC Standard MO-220, (SAW Singulation) fig . 1, VMMD.
2. Dimension and tolerance conform to ASMEY14.5M-1994.

2014-02-12

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**64M2**, 64-pad, 9 x 9 x 1.0mm Bod y, Lead Pitch 0.50mm , 7.65mm Exposed Pad, Micro Lead Frame Package (MLF)	64M2	E

11. Errata

11.1 ATmega640 rev. B

- **Inaccurate ADC conversion in differential mode with 200× gain**
- **High current consumption in sleep mode**

1. **Inaccurate ADC conversion in differential mode with 200× gain**

   With AVCC <3.6V, random conversions will be inaccurate. Typical absolute accuracy may reach 64 LSB.

   Problem Fix/Workaround

   None.

2. **High current consumption in sleep mode**

   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround

   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.2 ATmega640 rev. A

- **Inaccurate ADC conversion in differential mode with 200× gain**
- **High current consumption in sleep mode**

1. **Inaccurate ADC conversion in differential mode with 200× gain**

   With AVCC <3.6V, random conversions will be inaccurate. Typical absolute accuracy may reach 64 LSB.

   Problem Fix/Workaround

   None.

2. **High current consumption in sleep mode**

   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround

   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.3 ATmega1280 rev. B

- **High current consumption in sleep mode**

1. **High current consumption in sleep mode**

   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround

   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.4 ATmega1280 rev. A

- **Inaccurate ADC conversion in differential mode with 200× gain**
- **High current consumption in sleep mode**

1. **Inaccurate ADC conversion in differential mode with 200× gain**

   With AVCC <3.6V, random conversions will be inaccurate. Typical absolute accuracy may reach 64 LSB.

5. **IN/OUT instructions may be executed twice when Stack is in external RAM**

   If either an IN or an OUT instruction is executed directly before an interrupt occurs and the stack pointer is located in external ram, the instruction will be executed twice. In some cases this will cause a problem, for example:

   - If reading SREG it will appear that the I-flag is cleared.

   - If writing to the PIN registers, the port will toggle twice.

   - If reading registers with interrupt flags, the flags will appear to be cleared.

   Problem Fix/Workaround

   There are two application workarounds, where selecting one of them, will be omitting the issue:

   - Replace IN and OUT with LD/LDS/LDD and ST/STS/STD instructions.

   - Use internal RAM for stack pointer.

6. **EEPROM read from application code does not work in Lock Bit Mode 3**

   When the Memory Lock Bits LB2 and LB1 are programmed to mode 3, EEPROM read does not work from the application code.

   Problem Fix/Workaround

   Do not set Lock Bit Protection Mode 3 when the application code needs to read from EEPROM.

11.13 ATmega2561 rev. F

- **ADC differential input amplification by 46dB (200x) not functional**

1. **ADC differential input amplification by 46dB (200x) not functional**

   Problem Fix/Workaround

   None.

11.14 ATmega2561 rev. E

No known errata.

11.15 ATmega2561 rev. D

Not sampled.

11.16 ATmega2561 rev. C

- **High current consumption in sleep mode.**

1. **High current consumption in sleep mode**

   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround

   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.17 ATmega2561 rev. B

Not sampled.

11.18 ATmega2561 rev. A

- **Non-Read-While-Write area of flash not functional**
- **Part does not work under 2.4 Volts**
- **Incorrect ADC reading in differential mode**
- **Internal ADC reference has too low value**
- **IN/OUT instructions may be executed twice when Stack is in external RAM**
- **EEPROM read from application code does not work in Lock Bit Mode 3**

1. **Non-Read-While-Write area of flash not functional**

   The Non-Read-While-Write area of the flash is not working as expected. The problem is related to the speed of the part when reading the flash of this area.

   Problem Fix/Workaround

   - Only use the first 248K of the flash.

   - If boot functionality is needed, run the code in the Non-Read-While-Write area at maximum 1/4th of the maximum frequency of the device at any given voltage. This is done by writing the CLKPR register before entering the boot section of the code.

2. **Part does not work under 2.4 volts**

   The part does not execute code correctly below 2.4 volts.

   Problem Fix/Workaround

   Do not use the part at voltages below 2.4 volts.

3. **Incorrect ADC reading in differential mode**

   The ADC has high noise in differential mode. It can give up to 7 LSB error.

   Problem Fix/Workaround

   Use only the 7 MSB of the result when using the ADC in differential mode.

4. **Internal ADC reference has too low value**

   The internal ADC reference has a value lower than specified.

   Problem Fix/Workaround

   - Use AVCC or external reference.

   - The actual value of the reference can be measured by applying a known voltage to the ADC when using the internal reference. The result when doing later conversions can then be calibrated.

5. **IN/OUT instructions may be executed twice when Stack is in external RAM**

   If either an IN or an OUT instruction is executed directly before an interrupt occurs and the stack pointer is located in external ram, the instruction will be executed twice. In some cases this will cause a problem, for example:

   - If reading SREG it will appear that the I-flag is cleared.

   - If writing to the PIN registers, the port will toggle twice.

   - If reading registers with interrupt flags, the flags will appear to be cleared.

   Problem Fix/Workaround

   There are two application workarounds, where selecting one of them, will be omitting the issue:

   - Replace IN and OUT with LD/LDS/LDD and ST/STS/STD instructions.

- Use internal RAM for stack pointer.

6. **EEPROM read from application code does not work in Lock Bit Mode 3**

   When the Memory Lock Bits LB2 and LB1 are programmed to mode 3, EEPROM read does not work from the application code.

   Problem Fix/Workaround

   Do not set Lock Bit Protection Mode 3 when the application code needs to read from EEPROM.

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Atmel Corporation 1600 Technology Drive, San Jose, CA 95110 USA **T:** (+1)(408) 441.0311 **F:** (+1)(408) 436.4200 | **www.atmel.com**

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